



N-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^d	Q _g (Typ.)		
100	0.063 at V _{GS} = 10 V	6.8	9 nC		
100	0.084 at V _{GS} = 6 V	5.8	3110		

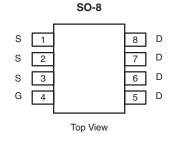
FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET[®] Power MOSFET
- 100 % UIS Tested

RoHS COMPLIANT HALOGEN

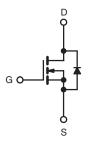
APPLICATIONS

- High Frequency Boost Converter
- LED Backlight for LCD TV



Ordering Information: Si4100DY-T1-E3 (Lead (Pb)-free)

Si4100DY-T1-GE3 (Lead (Pb)-free and Halogen-free)



N-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	100	V		
Gate-Source Voltage		V_{GS}	± 20	V	
	T _C = 25 °C		6.8		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		5.4		
Continuous Diam Current (1) = 150 °C)	T _A = 25 °C	l _D	4.4 ^{a, b}		
	T _A = 70 °C		3.5 ^{a, b}	^	
Pulsed Drain Current		I _{DM}	20	A	
Continuous Source-Drain Diode Current	T _C = 25 °C	I_	5		
	T _A = 25 °C	ls –	2.1 ^{a, b}		
Single Avalanche Current	L = 0.1 mH	I _{AS}	19		
Single Avalanche Energy		E _{AS}	18	mJ	
	T _C = 25 °C		6		
Maximum Dawar Dissination	T _C = 70 °C	P _D	3.8	w	
Maximum Power Dissipation	T _A = 25 °C		2.5 ^{a, b}	VV	
	T _A = 70 °C		1.6 ^{a, b}		
Operating Junction and Storage Temperature	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS								
Parameter	Symbol	Typical	Maximum	Unit				
Maximum Junction-to-Ambient ^{b, c}	t ≤ 10 s	R _{thJA}	37	50	°C/W			
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	17	21	O/ VV			

Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. $T_C = 25$ °C.

Vishay Siliconix



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 A		120		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 9			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	2		4.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current		$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	V, T _J = 55 °C		10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	20			Α	
		V _{GS} = 10 V, I _D = 4.4 A		0.051	0.063		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 6 \text{ V}, I_D = 3.8 \text{ A}$		0.069	0.084	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 4.4 A		10		S	
Dynamic ^b				l	l	<u> </u>	
Input Capacitance	C _{iss}			600			
Output Capacitance	C _{oss}	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		90		pF	
Reverse Transfer Capacitance	C _{rss}			50			
	Q _g	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 4.4 \text{ A}$		13.5	20	nC	
Total Gate Charge				9	13.5		
Gate-Source Charge	Q_{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 6 \text{ V}, I_{D} = 4.4 \text{ A}$		3			
Gate-Drain Charge	Q_{gd}			4.6			
Gate Resistance	R_{g}	f = 1 MHz		1		Ω	
Turn-On Delay Time	t _{d(on)}			15	25		
Rise Time	t _r	V_{DD} = 50 V, R_L = 14.3 Ω		12	20	- ns	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 3.5$ A, V_{GEN} = 6 V, R_g = 1 Ω		12	20		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			10	15		
Rise Time	t _r	V_{DD} = 50 V, R_L = 14.3 Ω		12	20		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 3.5$ A, V_{GEN} = 10 V, R_g = 1 Ω		15	25		
Fall Time	t _f			10	15		
Drain-Source Body Diode Characteristi	cs					•	
Continuous Source-Drain Diode Current	I _S	$T_C = 25 ^{\circ}C$			5	Δ	
Pulse Diode Forward Current	I _{SM}				20	A	
Body Diode Voltage	V _{SD}	I _S = 3.5 A, V _{GS} = 0 V		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			45	70	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 3.5 A, dI/dt = 100 A/μs, T _J = 25 °C		80	120	nC	
Reverse Recovery Fall Time	t _a	i _F = 3.3 A, αί/αι = 100 A/μs, 1 _J = 25 °C		33		ns	
Reverse Recovery Rise Time	t _b			12			

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing.

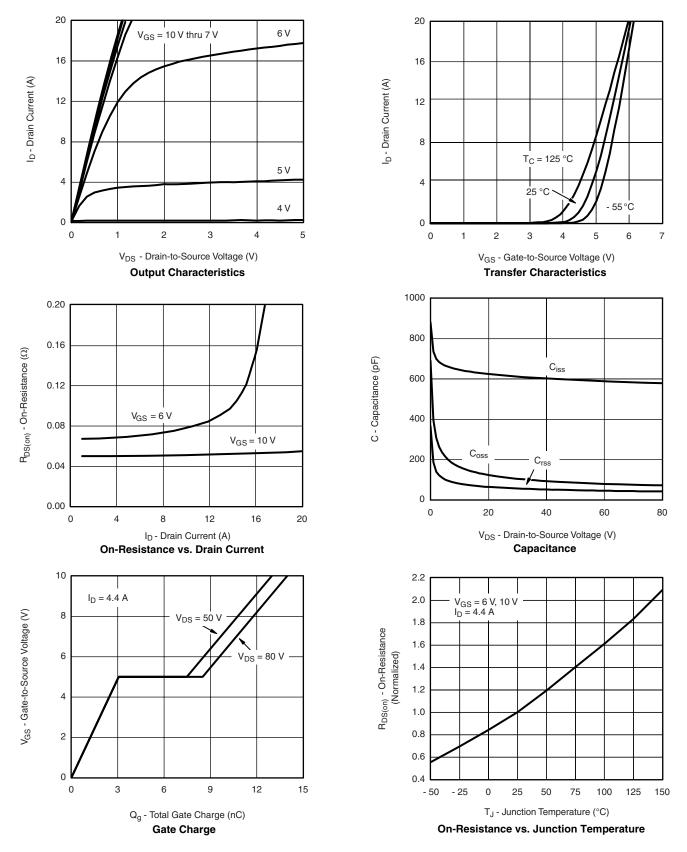
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





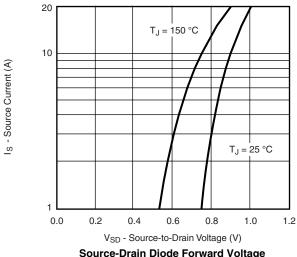


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

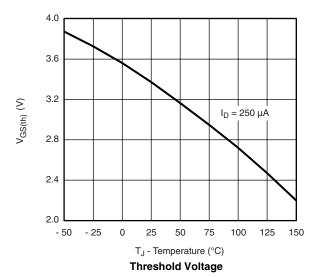


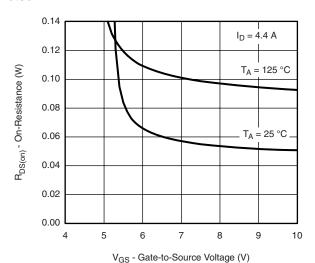
Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

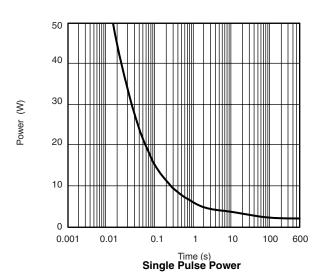


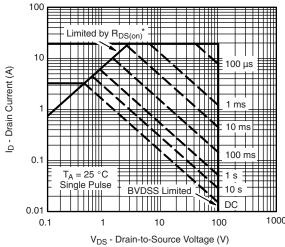
Source-Drain Diode Forward Voltage





On-Resistance vs. Gate-to-Source Voltage





 * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

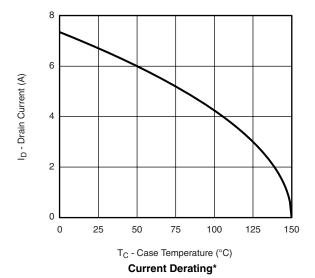
Safe Operating Area, Junction-to-Ambient

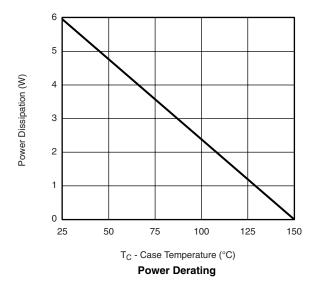






TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



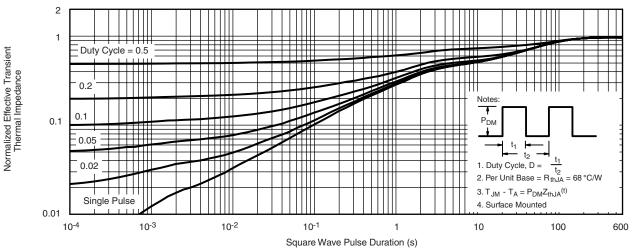


^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

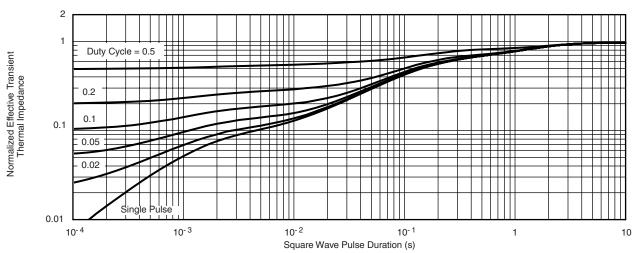
Vishay Siliconix



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?69251.



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	IETERS	INCHES		
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
Е	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I. 11-Sep-06					

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index

Ш



Legal Disclaimer Notice

Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

Revision: 13-Jun-16 1 Document Number: 91000

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Vishay:

Si4100DY-T1-E3 SI4100DY-T1-GE3